



Attorney's Docket No.: 06618-720001 / CIT-3325

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Eui-Hyeok Yang et al Art Unit : 2812
Serial No. : 10/005,765 Examiner : Unknown
Filed : November 2, 2001
Title : WAFER-LEVEL TRANSFER OF MEMBRANES IN SEMICONDUCTOR
PROCESSING

Commissioner for Patents
Washington, D.C. 20231

INFORMATION DISCLOSURE STATEMENT

Dear Sir:

Applicants call attention to the attached Information
Disclosure Statement and documents listed on form PTO-1449.

This filing is being made before the receipt of a first
Office action on the merits. No fee is required.

The documents are in the English language; hence no concise
explanation is necessary per Rule 98(a)(3).

Please apply any charges or credits to Deposit Account No.
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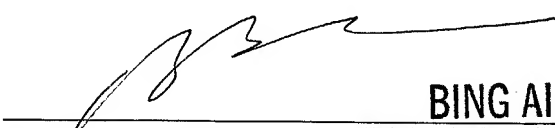
Date of Deposit March 28, 2002
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Consideration of the foregoing and enclosures plus the return of a copy of the enclosed form PTO-1449 with the Examiner's initials in the left column per MPEP 609 are earnestly solicited along with an early action on the merits.

Respectfully submitted,`

Date: March 28, 2002



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| Substitute Form PTO-1449 (Modified) APR 08 2002 PATENT MARK DESIG. (37 CFR § 1.98(b)) | U.S. Department of Commerce Patent and Trademark Office | | Attorney's Docket No. 06618-720001 | Application No. 10/005,765 |
| | Information Disclosure Statement by Applicant (Use several sheets if necessary) | | | |
| | Applicant Eui-Hyeok Yang and Dean V. Wiberg | | Filing Date November 2, 2001 | Group Art Unit 2812 |

U.S. Patent Documents

| Examiner Initial | Desig. ID | Patent Number | Issue Date | Patentee | Class | Subclass | Filing Date If Appropriate |
|------------------|-----------|---------------|------------|----------|-------|----------|----------------------------|
| | AA | | | | | | |
| | AB | | | | | | |
| | AC | | | | | | |
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| | AF | | | | | | |
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| | AH | | | | | | |
| | AI | | | | | | |

Foreign Patent Documents or Published Foreign Patent Applications

| Examiner Initial | Desig. ID | Document Number | Publication Date | Country or Patent Office | Class | Subclass | Translation | |
|------------------|-----------|-----------------|------------------|--------------------------|-------|----------|-------------|----|
| | | | | | | | Yes | No |
| | AJ | | | | | | | |
| | AK | | | | | | | |
| | AL | | | | | | | |

Other Documents (include Author, Title, Date, and Place of Publication)

| Examiner Initial | Desig. ID | Document |
|------------------|-----------|--|
| | AM | K.F. Harsh, W. Zhang, V.M. Bright and Y.C. Lee, "Flip-Chip Assembly for Si-Based RF MEMS", Proc. MEMS '99, Orlando, Florida, pp. 273-278, Jan 1999 |
| | AN | T. Akiyama, U. Stzuffer and N de Rooij, "Wafer-and Piece-Wise Si Tip Transfer Technologies for Applications in Scanning Probe Microscopy", IEEE Journal of Microelectromechanical Systems, pp. 65-70, 1999 |
| | AO | A. Singh, D.A. Horsley, M. Cohn, A. Pisano and R.T. Howe, "Batch Transfer of Microstructures using Flip-Chip Solder Bonding", IEEE Journal of Microelectromechanical Systems, pp. 27-33 1999. |
| | AP | H. Nguyen, P. Patterson, H. Toshiyoshi and M.C. Wu, "A Substrate-Independent Wafer Transfer Technique for Surface-Micromachined Devices", Proc MEMS Conference, 2000 |

Examiner Signature

Date Considered

EXAMINER: Initials citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.